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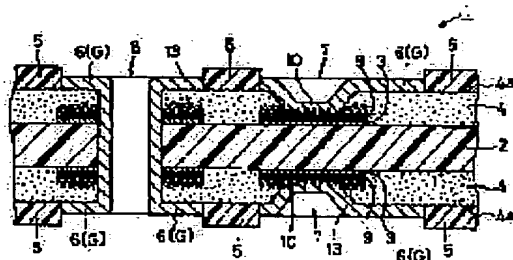
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UNO HIROAKI**(54) MULTILAYER PRINTED WIRING BOARD AND MANUFACTURING METHOD THEREOF****(57)Abstract:**

PROBLEM TO BE SOLVED: To provide a multilayer printed wiring board superior in appearance and reliability even under high temp. high pressure and high humidity conditions.

SOLUTION: A multilayer printed wiring board 1 has an inner conductor pattern 3 having a finely roughed layer 9 at the surface and interlayer insulation layer 4 disposed between the inner and outer conductor patterns 3, 6. A rust-preventing agent 13 is disposed between these layers 9, 4 and applied to the surface of a metal or precious metal layer contg. at least one metal having a higher ionization tendency than Cu and lower than Ti; this metal layer being formed on the surface of the surface layer 9 of the pattern 3.

**LEGAL STATUS**

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